

HSP

NOTES:

Current Rating: 3.0AMP
 Withstand Voltage: 500V AC/DC
 Contact Resistance: 20mΩ Max
 Insulation Resistance: 1000MΩMin
 Operation Temperature: -40°C to +105°C

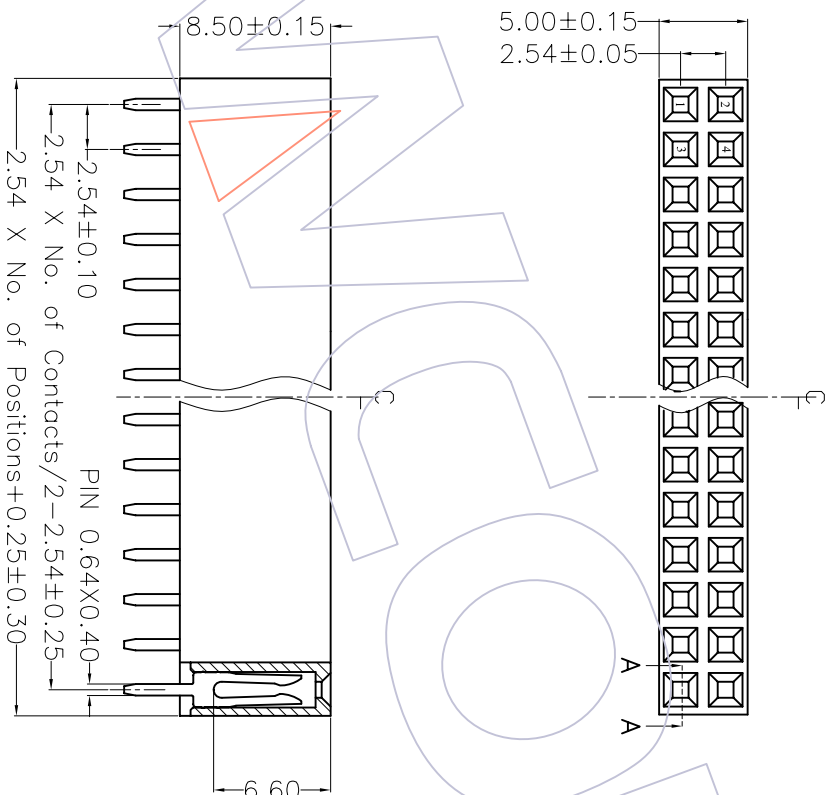
Contact Material: Phosphor Bronze or Brass
 Contact plating: Au or Sn over Ni
 Insulator Material: PA6T or PBT+30%G.F UL94V-0

Ordering Information

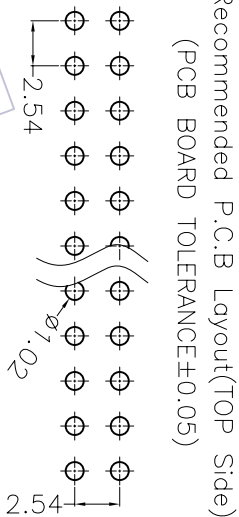
2185 - 2 XX S XX X YN A 1

No. of Pins per ROW: 02-40PIN
 Contact Plating: A=PBT, C=P60T
 Insulator: T=Tube, A=Tray
 Packing: T=Tube, A=Tray

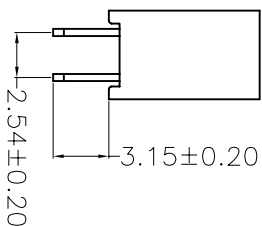
Gold Plating:
 G0=Gold Flash
 G1=3µ"Gold
 G2=5µ"Gold
 G3=9µ"Gold
 G4=15µ"Gold
 G5=30µ"Gold
 S0=Gold Flash/Tm
 S1=3µ"Gold/Tm
 S2=5µ"Gold/Tm
 S3=9µ"Gold/Tm
 S4=15µ"Gold/Tm
 S5=30µ"Gold/Tm
 SN=Tm



SECTION: A-A



Recommended P.C.B Layout(TOP Side)
 (PCB BOARD TOLERANCE±0.05)



REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE	OPERATION	DRAW	WEIXD	SCALE	UNIT	PART NO.	TITLE:
A0	08/03/13	NEW			X.X ±0.40	DESIGN	08.03.13	2.5:1	mm	2185 - 2XXSXXYYNA1	PH2.54 DUAL 180° H=8.50
					X.XX ±0.25	CHECK			A4		
					X.XXX ±0.15	APPROVE			1/1		
					Angle ± .3°	PROJ.				Customer NO.	

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